

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-11 (canceled).

12. (original): A method of manufacturing an liquid jetting head, comprising the steps of:

providing a first substrate, which defines a plurality of pressure generating chambers, the first substrate including a vibration plate which forms a first surface of the first substrate, and formed with a first through hole;

forming a plurality of piezoelectric elements on the vibration plate so as to associate with one of the pressure generating chambers, each piezoelectric element comprised of an upper electrode, a lower electrode and a piezoelectric layer provided between the upper electrode and the lower electrode;

providing a second substrate formed with a second through hole;

bonding the second substrate onto the first surface of the first substrate with an adhesive agent, while forming a coating layer comprised of a resin material on an inner wall face of a region at which the first through hole and the second through hole are to be connected; and

forming a communicating portion at which the first through hole and the second through hole are connected.

13. (original): The manufacturing method as set forth in claim 12, wherein the adhesive agent is extended so as to protruded from the inner wall face to form the coating layer.

14. (original): The manufacturing method as set forth in claim 12, wherein the communicating portion is formed by a mechanical processing.

15. (original): The manufacturing method as set forth in claim 12, wherein the communicating portion is formed by a laser processing.

16. (original): The manufacturing method as set forth in claim 12, further comprising the step of bonding a nozzle plate on a second surface of the first substrate opposing to the first surface, the nozzle plate formed with a plurality of nozzle orifices each communicated with one of the pressure generating chambers,

wherein the bonding step of the nozzle plate is performed before the forming step of the communicating portion.

17. (original): The manufacturing method as set forth in claim 12, wherein:
the steps are performed with respect to a wafer in which a plurality of first substrates are integrally formed; and

the respective first substrates are divided after the forming step of the communicating portion.

18. (original): The manufacturing method as set forth in claim 17, wherein the coating layer is formed on an outer peripheral face of a bonding surface of each first substrate and an associated second substrate.

PRELIMINARY AMENDMENT
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19. (original): The manufacturing method as set forth in claim 12, wherein:
the pressure chambers and the first through hole are formed by etching a silicon monocrystalline substrate; and
the upper electrode, the lower electrode and the piezoelectric layer are formed by at least one of the film-forming process or a lithographic process.
20. (original): The manufacturing method as set forth in claim 12, further comprising the step of covering the coating layer with a protective layer comprised of a resin material.